

CLAIMS**1. A film-like article comprising:**

a thin film integrated circuit which can store information described on the film-like article; and

5 an antenna connected to the thin film integrated circuit,

wherein the thin film integrated circuit and the antenna are mounted inside the film-like article.

2. A film-like article comprising:

10 a thin film integrated circuit which can store information described on the film-like article; and

an antenna connected to the thin film integrated circuit,

wherein the thin film integrated circuit is mounted inside the film-like article, and the antenna is mounted on a surface of the film-like article.

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3. A film-like article according to Claim 1,

wherein when the thickness of the film-like article is D, the position to dispose the thin film integrated circuit X may be set so as to satisfy $(1/2) \cdot D - 30 \mu\text{m} < X < (1/2) \cdot D + 30 \mu\text{m}$.

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4. A film-like article according to Claim 2,

wherein when the thickness of the film-like article is D, the position to dispose the thin film integrated circuit X may be set so as to satisfy $(1/2) \cdot D - 30 \mu\text{m} < X < (1/2) \cdot D + 30 \mu\text{m}$.

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5. A film-like article comprising:

a thin film integrated circuit which can store information described on the film-like article; and

an antenna connected to the thin film integrated circuit,

10 wherein the thin film integrated circuit and the antenna are mounted on a surface of the film-like article.

6. A film-like article comprising:

a thin film integrated circuit which can store information described on the 15 film-like article; and

an antenna connected to the thin film integrated circuit,

wherein the thin film integrated circuit is mounted on a surface of the film-like article, and

the antenna is mounted inside the film-like article.

7. A film-like article comprising a thin film integrated circuit which can store information described on the film-like article,
wherein the film-like article is provided with a depression, and
the thin film integrated circuit includes an antenna.

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8. A film-like article according to Claim 1,
wherein an opening with slits is provided in a connection area between the thin film integrated circuit and the antenna.

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9. A film-like article according to Claim 2,
wherein an opening with slits is provided in a connection area between the thin film integrated circuit and the antenna.

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10. A film-like article according to Claim 5,
wherein an opening with slits is provided in a connection area between the thin film integrated circuit and the antenna.

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11. A film-like article according to Claim 6,
wherein an opening with slits is provided in a connection area between the thin film integrated circuit and the antenna.

12. A film-like article according to Claim 7,
wherein an opening with slits is provided in a connection area between the thin
film integrated circuit and the antenna.

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13. A film-like article according to Claim 1,
wherein the thin film integrated circuit has light-transmitting characteristic.
14. A film-like article according to Claim 2,
wherein the thin film integrated circuit has light-transmitting characteristic.

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15. A film-like article according to Claim 5,
wherein the thin film integrated circuit has light-transmitting characteristic.

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16. A film-like article according to Claim 6,
wherein the thin film integrated circuit has light-transmitting characteristic.

17. A film-like article according to Claim 7,
wherein the thin film integrated circuit has light-transmitting characteristic.

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18. A film-like article according to Claim 1,

wherein the thin film integrated circuit has an insulating film containing nitrogen.

19. A film-like article according to Claim 2,

5 wherein the thin film integrated circuit has an insulating film containing nitrogen.

20. A film-like article according to Claim 5,

wherein the thin film integrated circuit has an insulating film containing nitrogen.

10 21. A film-like article according to Claim 6,

wherein the thin film integrated circuit has an insulating film containing nitrogen.

22. A film-like article according to Claim 7,

wherein the thin film integrated circuit has an insulating film containing nitrogen.

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23. A film-like article according to Claim 1,

wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3

μm .

20 24. A film-like article according to Claim 2,

wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .

25. A film-like article according to Claim 5,
5 wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .

26. A film-like article according to Claim 6,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3
10 μm .

27. A film-like article according to Claim 7,
wherein thickness of the thin film integrated circuit is in a range of 0.1 μm to 3 μm .

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28. A film-like article according to Claim 1,
wherein the thin film integrated circuit has a semiconductor film containing
hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

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29. A film-like article according to Claim 2,

wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

30. A film-like article according to Claim 5,
5 wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

31. A film-like article according to Claim 6,
10 wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

32. A film-like article according to Claim 7,
15 wherein the thin film integrated circuit has a semiconductor film containing hydrogen of 1×10^{19} atoms/cm³ to 5×10^{20} atoms/cm³.

33. A film-like article according to any one of Claims 28 to 32,
20 wherein the semiconductor film includes a source, a drain, and a channel region,
and
the source, the drain, and the channel region are provided perpendicular to
direction of bending the film-like article.

34. A film-like article according to Claim 1,

wherein the film-like article comprises a plurality of thin film integrated circuits,

and

5 the plurality of thin film integrated circuits are integrated with antennas.

35. A film-like article according to Claim 2,

wherein the film-like article comprises a plurality of thin film integrated circuits,

and

10 the plurality of thin film integrated circuits are integrated with antennas.

36. A film-like article according to Claim 5,

wherein the film-like article comprises a plurality of thin film integrated circuits,

and

15 the plurality of thin film integrated circuits are integrated with antennas.

37. A film-like article according to Claim 6,

wherein the film-like article comprises a plurality of thin film integrated circuits,

and

20 the plurality of thin film integrated circuits are integrated with antennas.

38. A film-like article according to Claim 7,

wherein the film-like article comprises a plurality of thin film integrated circuits,

and

5 the plurality of thin film integrated circuits are integrated with antennas.

39. A film-like article according to Claim 1,

wherein the film-like article is a business card.

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40. A film-like article according to Claim 2,

wherein the film-like article is a business card.

41. A film-like article according to Claim 5,

wherein the film-like article is a business card.

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42. A film-like article according to Claim 6,

wherein the film-like article is a business card.

43. A film-like article according to Claim 7,

20 wherein the film-like article is a business card.

44. A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

5 cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated circuits;

and

enfolding the thin film integrated circuits and the antenna in a base member of the

10 film-like article.

45. A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

15 cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated circuits;

and

mounting the thin film integrated circuits and the antenna on a surface of a base

20 member of the film-like article.

46. A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

5 cutting the second substrate to cut out each of the plurality of thin film integrated circuits;

connecting an antenna to a connection terminal of the thin film integrated circuits;

and

mounting the thin film integrated circuits and the antenna in a depression on a

10 surface of a base member of the film-like article.

47. A method for manufacturing a film-like article, comprising the steps of:

forming a plurality of thin film integrated circuits over a first substrate;

transferring the plurality of thin film integrated circuits to a second substrate;

15 cutting the second substrate to cut out each of the plurality of thin film integrated circuits; and

enfolding the thin film integrated circuit in a base member of the film-like article,

forming an antenna on a surface of the base member of the film-like article so that

the thin film integrated circuits and the antenna are connected through an opening formed

20 on the base member of the film-like article.

48. A method for manufacturing a film-like article, comprising the step of forming an antenna on a surface of a base member of the film-like article so that a plurality of thin film integrated circuits and the antenna are connected through an opening formed 5 on the base member of the film-like article,
wherein a plurality of thin film integrated circuits are formed over a first substrate,
the plurality of thin film integrated circuits are transferred to a second substrate,
and
10 the second substrate is cut so as to cut out the plurality of thin film integrated circuits.